

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0443800001](#)
Status: **Active**
Overview: [modular_plugs_jacks](#)
Description: Modular Jack, Right Angle, Low Profile, Inverted, 8/8, Unshielded

Documents:
[3D Model](#) [Product Specification PS-43860-003 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Application Specification \(PDF\)](#)

Agency Certification

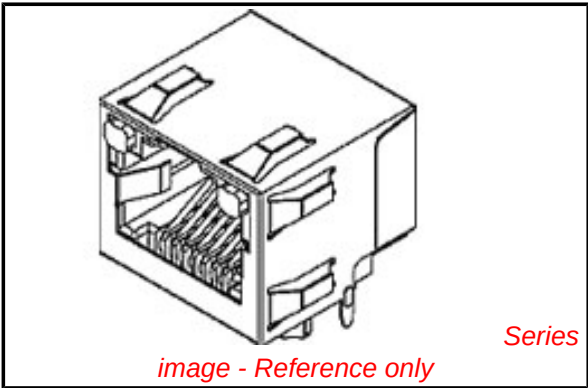
CSA LR19980
UL E107635

General

Product Family Modular Jacks/Plugs
Series [44380](#)
Component Type PCB Jack
Magnetic No
Overview [modular_plugs_jacks](#)
Performance Category 3
Power over Ethernet (PoE) N/A
Product Name RJ45

Physical

Boot Color N/A
Color - Resin Black
Durability (mating cycles max) 500
Inverted / Top Latch Yes
Keying to Mating Part None
Lightpipes/LEDs None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Orientation Right Angle (Side Entry)
PCB Locator Yes
PCB Retention Yes
PCB Thickness Recommended (in) 0.039 In
PCB Thickness Recommended (mm) 1.00 mm
Packaging Type Tube
Panel Mount Without Flange
Pitch - Mating Interface (in) 0.040 In
Pitch - Mating Interface (mm) 1.02 mm
Pitch - Term. Interface (in) 0.040 In
Pitch - Term. Interface (mm) 1.02 mm
Plating min: Mating (µin) 50
Plating min: Mating (µm) 1.25
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Ports 1
Positions / Loaded Contacts 8/8
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -40°C to +85°C
Termination Interface: Style Through Hole
Waterproof / Dustproof No



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[44380Series](#)

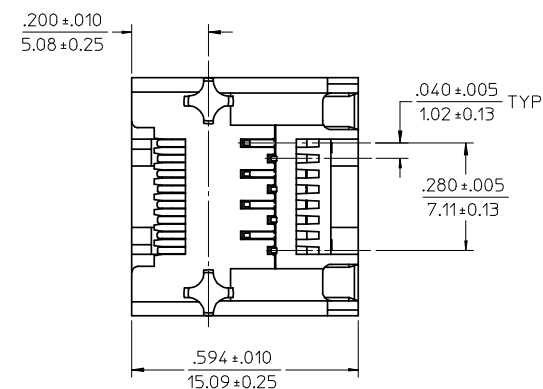
Mates With
FCC 68 Plugs

Wire/Cable Type	N/A
Electrical	
Current - Maximum per Contact	1.5A
Grounding to PCB	No
Grounding to Panel	None
Shielded	No
Voltage - Maximum	150V AC (RMS)
Solder Process Data	
Lead-free Process Capability	Wave Capable (TH only)
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-43860-004
Product Specification	PS-43860-003, RPS-43860-004, RPS-43860-007, RPS-43860-008, RPS-43860-013
Sales Drawing	SD-44380-001

This document was generated on 06/08/2010

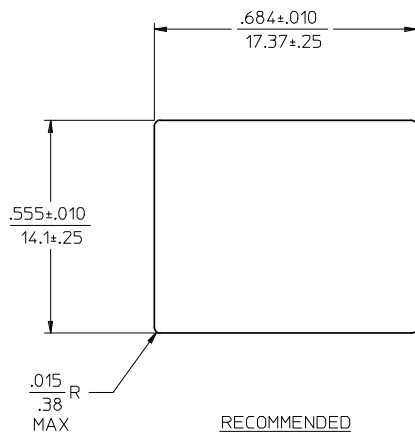
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7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

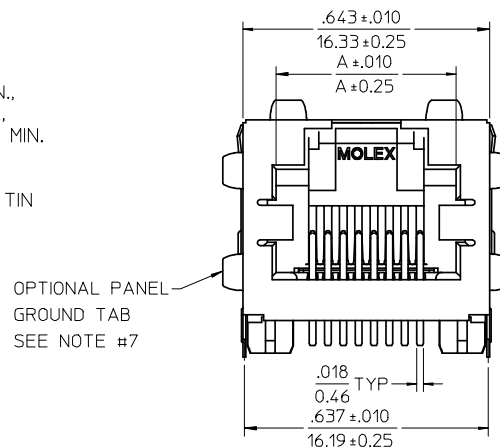


SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)		
 MOLEX INCORPORATED		
DOCUMENT NO. SD-44380-001	SHEET NO. 1 OF 5	

- NOTES
- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
 - 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT
TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN
PRODUCT WITH TIN-LEAD IN THE PC TAIL AREA.
 - 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
 - 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005
OPTION (44380-2004) PACKAGED IN TAPE AND REEL
 - 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR
REFERENCE ONLY
 - 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS
 - 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE
ASSEMBLY MATERIAL NUMBER TABLE.
 - 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

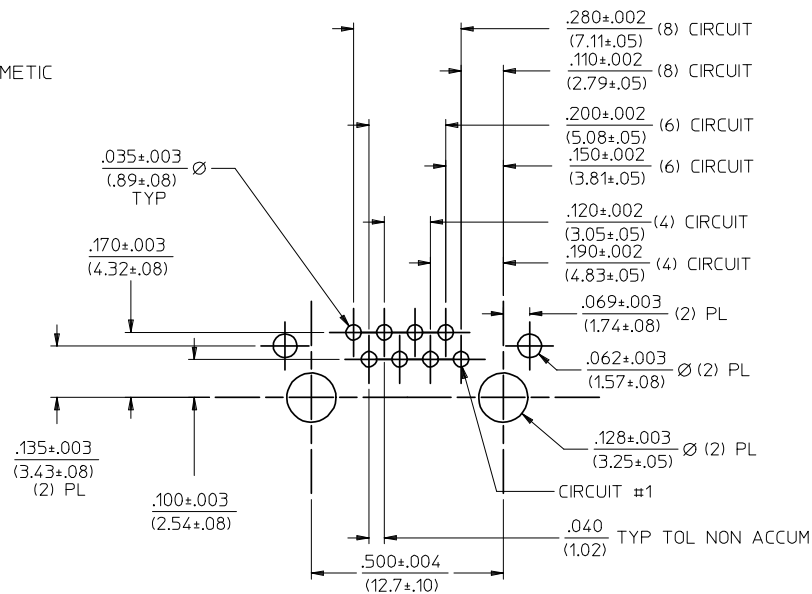
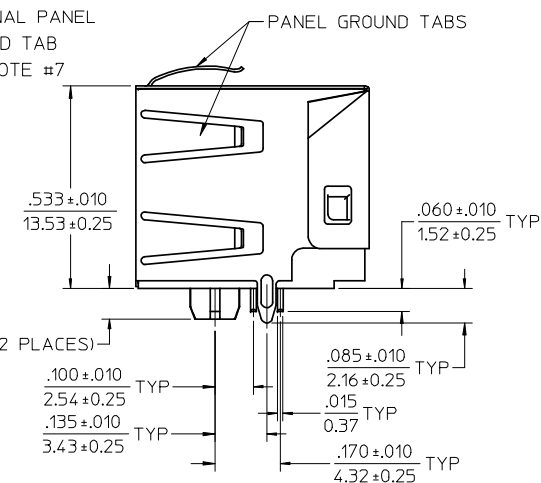


RECOMMENDED
PANEL
OPENING

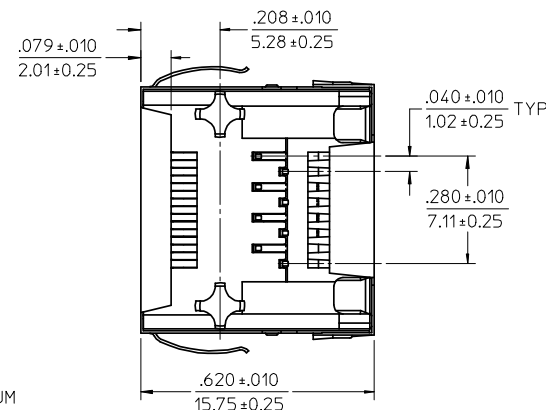


OPTIONAL PANEL
GROUND TAB
SEE NOTE #7

OPTIONAL PANEL
GROUND TAB
SEE NOTE #7



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00



MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0004	8	.470/11.94	8	ALL
44380-0005	6	.389/9.88	6	ALL
44380-0006	6	.389/9.88	4	ALL
44380-0013	8	.470/11.94	8	SEE NOTE #7
44380-0014	6	.389/9.88	6	SEE NOTE #7
44380-0015	6	.389/9.88	4	SEE NOTE #7
44380-2004	8	.470/11.94	8	ALL

QUALITY SYMBOLS	DESCRIPTION
▽=0	SEE SHEET 1
▽=0	EC NO: UCP2008-0965
	DRWN:JBELL 2007/11/08
	CHKD:LSCHMIDT 2007/12/04
	APPR:FSM/TH 2007/12/05
REV	

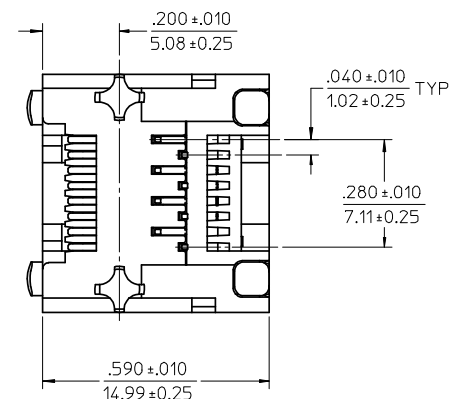
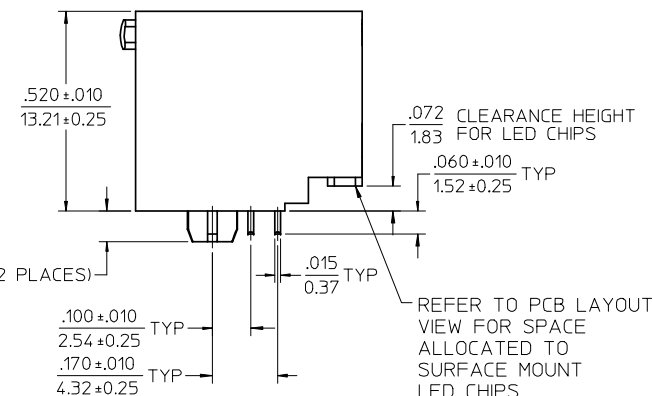
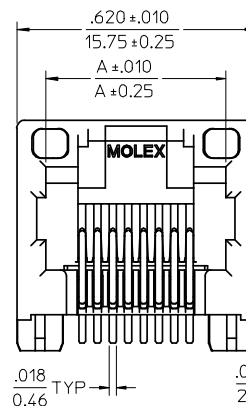
GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± --- ± ---
1 PLACE ± --- ± ---
ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
IN/MM	4:1	INCH	
DRAWN BY	DATE	TITLE	
MAYO	1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)	
CHECKED BY	DATE		
ROBERTS	1999/04/09		
APPROVED BY	DATE		
ROBERTS	1999/04/09		
MATERIAL NO.	DOCUMENT NO.		

MOLEX INCORPORATED	SD-44380-001	SHEET NO. 2 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

NOTES

- 1) MATERIAL:
HOUSING:
GLASS FILLED NYLON, 94V-0, COLOR: BLACK
TERMINALS:
PHOSPHOR BRONZE, .015/(0.38) THK
LIGHTPIPE:
POLYCARBONATE- WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) PLATING:
TERMINAL:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT
TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN
PRODUCT WITH TIN-LEAD IN THE PC TAIL AND/OR SHIELD.
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING:
PER PACKAGING SPECIFICATION PK-43860-004
- 5) APPLICATION SPECIFICATION: AS-43860-001.
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) REFER TO PAGE (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0007	POLYCARBONATE	8	.470/11.94	8
44380-0008	POLYCARBONATE	6	.389/9.88	6
44380-0009	POLYCARBONATE	6	.389/9.88	4
44380-0020	POLYSULFONE	8	.470/11.94	8
44380-0021	POLYSULFONE	6	.389/9.88	6
44380-0022	POLYSULFONE	6	.389/9.88	4

SEE SHEET 1	EC NO: UCP2008-0965	2007/11/08	DRWN:JBELL
		2007/12/04	CHKD:LSCHMIDT
		2007/12/05	APPR:FSMITH
REV	DESCRIPTION		

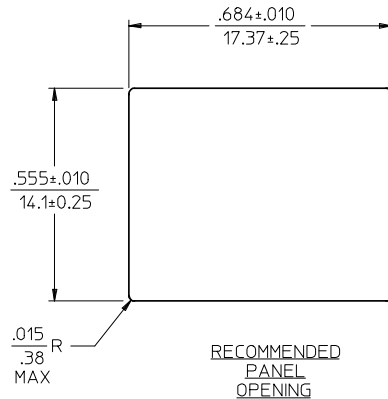
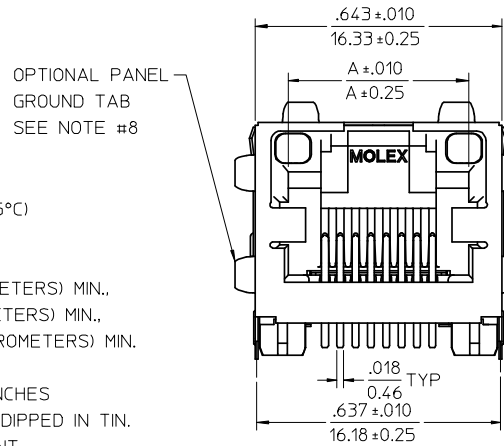
QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± --- ± ---
1 PLACE ± --- ± ---
ANGULAR ±1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

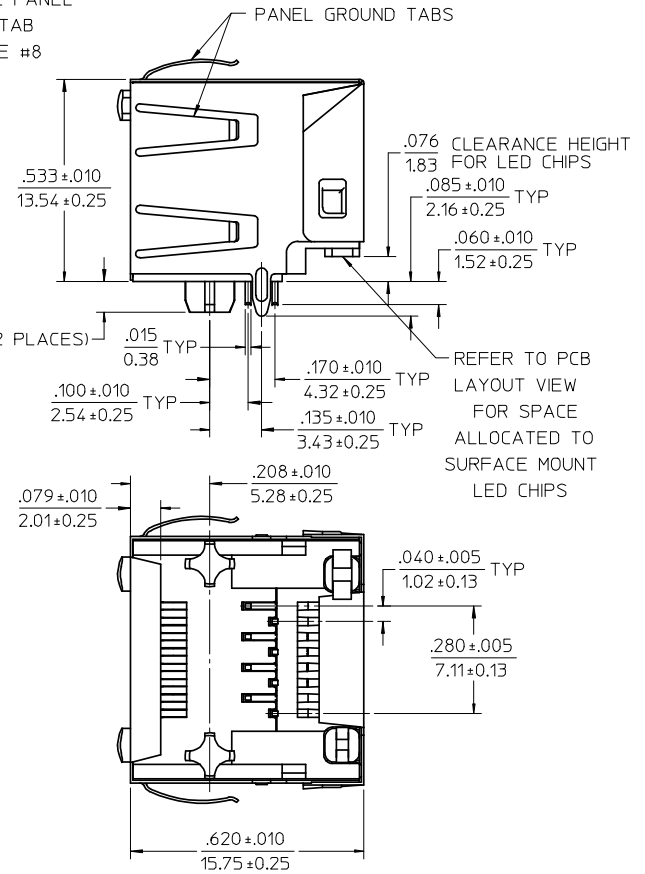
DIMENSION STYLE IN/MM
DRAWN BY MAYO 1999/04/09
CHECKED BY ROBERTS 1999/04/09
APPROVED BY ROBERTS 1999/04/09
MATERIAL NO.
SIZE

SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
TITLE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)	
	MOLEX INCORPORATED	
DOCUMENT NO.	SD-44380-001	SHEET NO. 3 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

- NOTES
- 1) MATERIAL:
- HOUSING:
- GLASS FILLED NYLON, 94V-0, COLOR: BLACK
- TERMINALS:
- PHOSPHOR BRONZE, .015/(0.38) THK
- SHIELD:
- BRASS
- LIGHTPIPE:
- POLYCARBONATE - WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
- POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) PLATING:
- TERMINAL:
- SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- SHIELD:
- *100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
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- 3) PRODUCT SPECIFICATION:
- CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003.
- 4) PACKAGING:
- CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005 .
- 5) APPLICATION SPECIFICATION: AS-43860-001.
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR
REFERENCE ONLY.
- 7) CONFORMS TO F.C.C. REGULATION PART 68.5
FOR MODULAR JACKS.
- 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE
ASSEMBLY MATERIAL NUMBER TABLE.
- 9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



OPTIONAL PANEL
GROUND TAB
SEE NOTE #8



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONN SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0010	POLYCARBONATE	8	.470/11.94	8	ALL
44380-0011	POLYCARBONATE	6	.389/9.88	6	ALL
44380-0012	POLYCARBONATE	6	.389/9.88	4	ALL
44380-0016	POLYCARBONATE	8	.470/11.94	8	SEE NOTE #8
44380-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
44380-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
44380-1010	POLYSULFONE	8	.470/11.94	8	ALL
44380-1011	POLYSULFONE	6	.389/9.88	6	ALL
44380-1012	POLYSULFONE	6	.389/9.88	4	ALL
44380-1016	POLYSULFONE	8	.470/11.94	8	SEE NOTE #8
44380-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
44380-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1
EC NO: WCP2008-0965
DRWN:JBELL 2007/11/08
CHKD:LSCHMIDT 2007/12/04
APPR:FSM/TH 2007/12/05

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	---	---
3 PLACES ±	---	---
2 PLACES ±	---	---
1 PLACE ±	---	---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY DATE
MAYO 1999/04/09

CHECKED BY DATE
ROBERTS 1999/04/09

APPROVED BY DATE
ROBERTS 1999/04/09

MATERIAL NO.
SEE CHART

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE PROJECTION

INVERTED MODULAR
JACK ASSEMBLY
(MINI-PCI COMPLIANT)

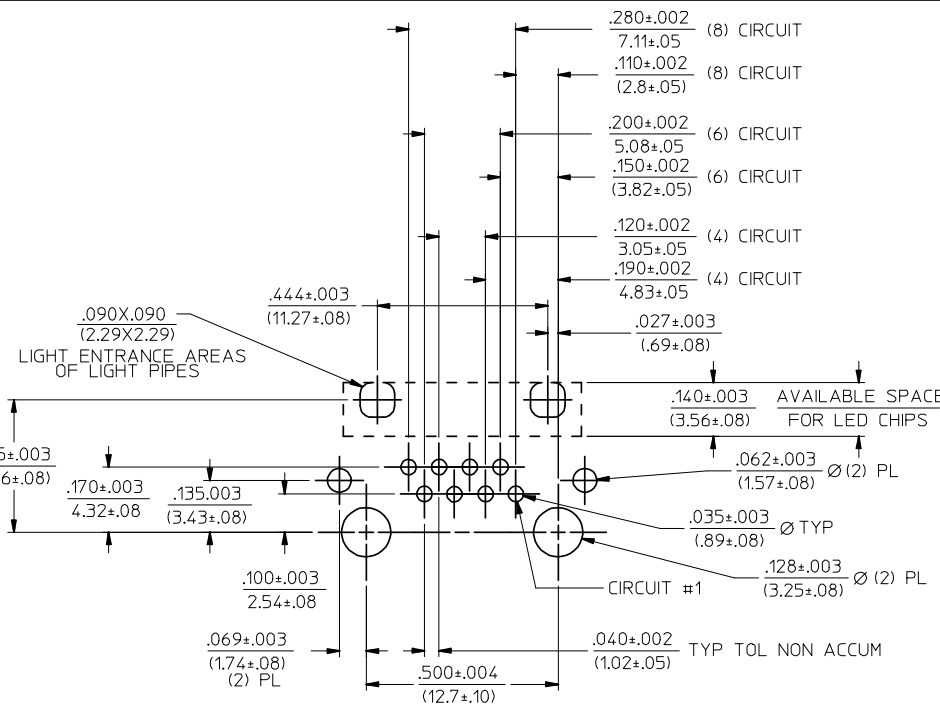
MOLEX INCORPORATED

DOCUMENT NO.
SD-44380-001

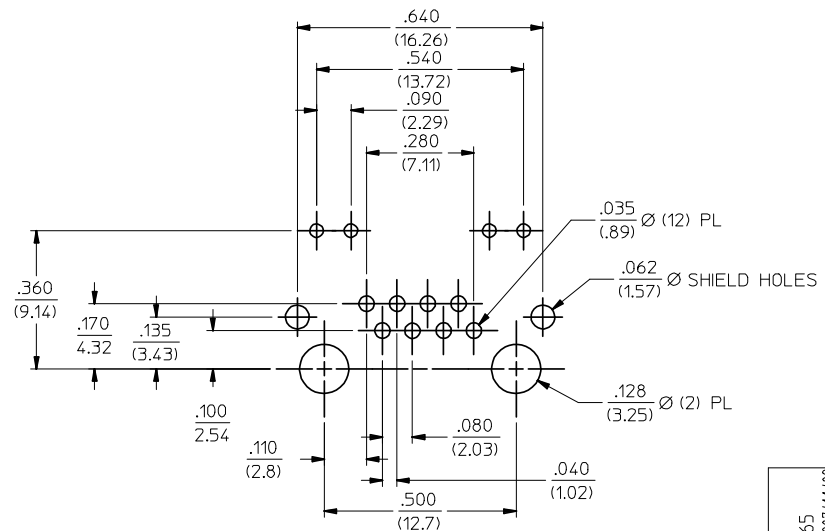
SHEET NO.
4 OF 5

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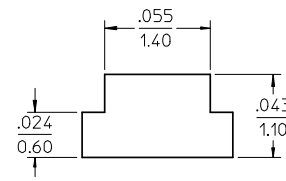
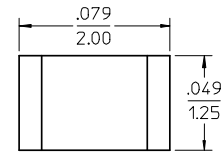
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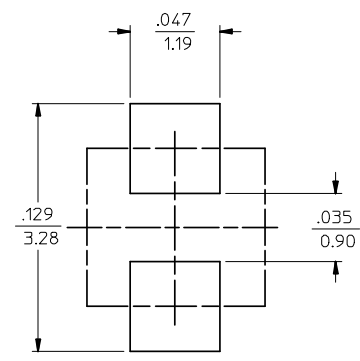
MOLEX RECOMMENDED
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00



TYPICAL COMPETITION
PCB LAYOUT WITH
INTEGRAL LED'S
(SHOWN FOR REFERENCE ONLY)
RECOMMENDED PC BOARD THICKNESS: .039/1.00



RECOMMENDED SMT
LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1 EC NO: UCP2008-0965 DRWN:JBELL 2007/11/08 CHKD:LSCHMIDT 2007/12/04 APPR:FSMITH 2007/12/05	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
					IN/MM		4:1	INCH		
				mm	INCH	DRAWN BY	DATE	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)		
			4 PLACES	± ---	± ---	MAYO	1999/04/09			
			3 PLACES	± ---	± ---	CHECKED BY	DATE			
			2 PLACES	± ---	± ---	ROBERTS	1999/04/09			
			1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED		
			ANGULAR ±1/2°		ROBERTS	1999/04/09				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
					SEE CHART		SD-44380-001		5 OF 5	
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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E-mail: info@moschip.ru

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moschip.ru_6

moschip.ru_9